

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claims 1-8 (canceled).

Claim 9. (currently amended) A method of making a chip device, the method comprising:

providing a die having a first surface with a drain connection and a second surface opposite the first surface;

providing a leadframe including a major surface defining at least part of a die attach cavity and a plurality of dimples defined around a periphery of the leadframe, the die attach cavity having substantially the same thickness as the die;

placing solder in balls into the dimples; and

flipping placing the die in into the die attach cavity and attaching the die to the leadframe therein, wherein the first surface including the drain connection is electrically coupled to the major surface defining at least part of the die attach cavity and the solder in the dimples of the leadframe

~~wherein the die comprises a MOSFET.~~

Claim 10. (currently amended) The method of claim 9 wherein the die ~~provided~~ is a bumped die.

Claim 11. (canceled)

Claim 12. (currently amended) The method of claim 9 wherein the second surface of the die includes source and gate connections and wherein the method further comprises ~~comprising~~ placing solder on the die source and gate connections.

Claim 13. (previously presented) The method of claim 9 wherein the leadframe comprises a copper based alloy.

Claim 14. (previously presented) The chip device of claim 9 wherein the leadframe includes a solderable coating.

Claim 15. (canceled)

Claim 16. (previously presented) The method of claim 9 wherein the leadframe comprises a Ni-Pd coating.

Claim 17. (canceled)

Claim 18. (previously presented) The method of claim 9 wherein the step of attaching the die is performed such that the die is coplanar with a top surface of the leadframe.

Claim 19. (previously presented) The method of claim 9 further comprising the step of adding a solderable coating to the leadframe.

Claim 20. (previously presented) The method of claim 9 wherein the leadframe is conductive.

Claim 21. (previously presented) The method of claim 20 wherein the conductive leadframe comprises a copper based alloy.

Claim 22. (new) The method of claim 9 wherein the die comprises a MOSFET.

Claim 23. (new) The method of claim 9 wherein the cavity has a square shape.